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Atty. Docket No. CPAC 1017-2  
Appl. No. 10/632,549

AUG 03 2004  
**OFFICIAL**

PATENT

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Marcos Karnezos

Application No.: 10/632,549

Filed: August 2, 2003

Title: **Semiconductor multi-package module having  
wire bond interconnect between stacked  
packages**

) Examiner: Phat X. CAO


) Group Art Unit: 2569

) Date: August 3, 2004

) **CERTIFICATE OF FACSIMILE TRANSMISSION**

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United States Patent and Trademark Office, at the  
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Signed

  
Paula Faulk Hurley

**RESPONSE TO RESTRICTION REQUIREMENT**

Dear Sir:

Responsive to the Office action mailed July 22, 2004 (Restriction only), Applicants elect:  
Group I, claims 1 - 10.

**Amendments to the Specification** begin on page 2 of this paper.

There are no amendments to the claims. A **Listing of Claims** is included for the  
Examiner's convenience, beginning on page 3 of this paper.

**Remarks** begin on page 5 of this paper.